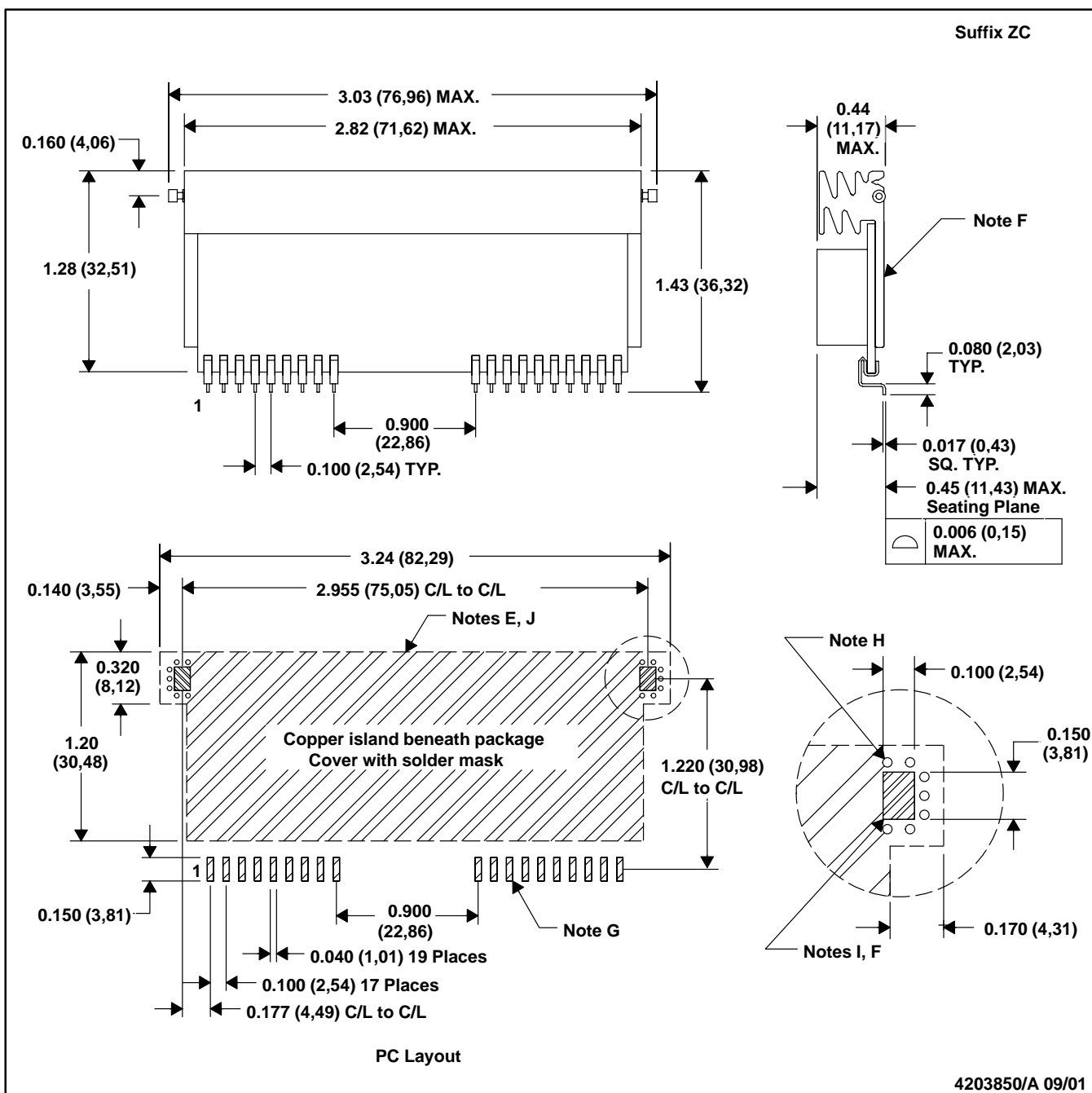


EHL (R-MSIP-G19)

METAL SINGLE-IN-LINE MODULE



- NOTES:
- All linear dimensions are in inches (mm).
 - This drawing is subject to change without notice.
 - 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 - 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 - Recommended mechanical keep out area.
 - The heatsink is isolated but electrically conductive. No signal traces are allowed under the heatsink area. A solid copper island is recommended, which can be electrically connected to secondary ground.

- Power pin connections should utilize two or more vias per input, ground and output pin.
- Vias are recommended to improve copper adhesion.
- Solder mask openings to copper island for solder joints to mechanical pins.

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